Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.025”**

**ANODE**

**.018 X .018”**

**DO NOT BOND**

**.025”**

**For Zener operation, cathode must be operated positive with respect to anode.**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .018” X .018”**

**Backside Potential: Cathode**

**APPROVED BY: DK DIE SIZE .025” X .025” DATE: 11/3/21**

**MFG: MOTOROLA THICKNESS .008” P/N: 1N4616**

**DG 10.1.2**

#### Rev B, 7/19/02